## **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **LISTING OF CLAIMS:**

- 1-9. (Cancelled)
- 10. (New) A method for laser drilling comprising:

acting upon a region of a workpiece by a laser beam, so that a hole is produced in the region;

implementing the method under an adjustable process-gas atmosphere in such a way that, due to a reciprocal action between the laser beam and a process gas, plasma forms in at least one of the region and the hole acted upon by the laser beam; and

arranging a backing at an outlet opening of the hole produced by the laser beam.

- 11. (New) The method according to claim 10, wherein an inert gas, with an addition of noble gases, is used as the process gas.
- 12. (New) The method according to claim 11, wherein the inert gas includes nitrogen, and the noble gases include at least one of helium and argon.
- 13. (New) The method according to claim 10, further comprising pressurizing the process gas at a pressure of maximally 1.5 bar.
- 14. (New) The method according to claim 10, further comprising adjusting an impingement direction of the process gas by tilting relative to a direction of the laser beam, a tilting angle being up to 15°.
- 15. (New) The method according to claim 10, wherein a material used for the backing has at least one of thermal and optical properties that influence a form of the outlet opening, the material including at least one of a metallic material and a copper-containing material.

- 16. (New) The method according to claim 10, wherein the backing is arranged at a distance from at least one of the outlet opening and the workpiece that influences a form of the outlet opening, the distance being between 20 µm and 200 µm.
- 17. (New) The method according to claim 10, wherein the backing is arranged with tilting at a predetermined angle with respect to at least one of the outlet opening and the workpiece, the tilting influencing a form of the outlet opening, the tilting angle being up to 20°.
- 18. (New) A device for laser drilling comprising:

means for acting upon a region of a workpiece by a laser beam so as to produce a hole; and

means for adjusting a process-gas atmosphere in at least one of the region and the hole acted upon by the laser beam, in such a way that, due to a reciprocal action between the laser beam and a process gas, plasma forms in at least one of the region and the hole acted upon by the laser beam, a backing being able to be positioned at an outlet opening of the produced hole.

19. (New) The device according to claim 18, wherein the means for adjusting the process-gas atmosphere includes at least one gas nozzle.